



Substrate Ball Pad Metallization Change for Defense-Grade Virtex-6Q Flip Chip RF Packages

XCN13011 (v1.0) April 22, 2013

Product Change Notice – For Information Only

Overview

The purpose of this notification is to communicate that Xilinx will convert the substrate ball pad metallization from Nickel/Gold plating to Eutectic Cu Solder on Pad (SOP) for Defense-Grade Virtex®-6Q FPGA flip chip RF packages. There is no change to the fit, form, or function.

Description

Xilinx has qualified an additional substrate ball pad metallization called Eutectic Cu Solder on Pad (SOP) for Virtex-6Q FPGA flip chip RF packages. The implementation of Eutectic CuSOP is an industry trend with our substrate suppliers converting from Ni/Au ball pad metallization to SOP metallization. This enables Xilinx to better support long-term customer demand. Xilinx will begin cross shipping Virtex-6Q FPGA RF products upon the release of this notification.

There is no change in the fit, form or function with this change. There is no change to the package substrate and solder balls.

Products Affected

This change affects all speed, package, and temperature variations of the Defense-Grade Virtex-6Q FPGA devices. Affected part numbers are included in the following table(s):

Table 1: Virtex-6Q FPGA Product Changes

Xilinx Product	Package	Xilinx Product	Package
XQ6VLX130T	RF784	XQ6VLX550T	RF1759
XQ6VLX130T	RF1156	XQ6VSX315T	RF1156
XQ6VLX240T	RF784	XQ6VSX315T	RF1759
XQ6VLX240T	RF1156	XQ6VSX475T	RF1156
XQ6VLX240T	RF1759	XQ6VSX475T	RF1759

Key Dates and Ordering Information

Xilinx will begin to cross-ship Virtex-6Q FPGA flip chip RF packages with this change starting 90 days after release of this notification.

Qualification Data

Xilinx has completed and successfully passed all the necessary qualifications.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
4/22/13	1.0	Initial release.

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